

## **SPECIFICATION SHEET**

	1	
SPECIFICATION SHEET NO.	R0717- YR32K76800S005	
DATE	July 17, 2	024
REVISION	А3	Updated With Most Recent Data
DESCRIPTION AND		Crystals, L3.2*W1.5*H0.9mm, 2 Pads, YR series KHz, ±20ppm, CL 9pF
MAIN PARAMETRICS	Operating	g Temp. Range -40°C ~+85°C, ESR 70 Kohm Max.,
	Reflow Pr	ofile Condition 260 °C Max.
	Tape/Reel, 3000pcs/Reel, RoHS/RoHS III compliant	
CUSTOMER		
CUSTOMER PART NO.		
CROSS REF. PART NO.		
ORIGINAL MFG/PART NO.	TGS/CCMM 32K768A20-9-40-70T LF	
PART CODE	YR32K76800S005	

#### **VENDOR APPROVE**

Issued/Checked/Approved

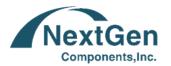






DATE: July 17, 2024

CUSTOMER APPROVE		
DATE:		



# **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

#### **MAIN FEATURE**

- SMD Package, L3.2\*w1.5\*h0.9mm, 2 Pads
- Industry Standard
- Reflow Profile Condition 260 °C Max.
- Cross More Competitors Part
- REACH/RoHS III Compliant





#### **APPLICATION**

• Small Communications Devices And More

### **HOW TO ORDER**

Please follow up Part Code Guide and Indicate Part Code When You Order Or RFQ.

#### **PART CODE GUIDE**

RFQ
Request For Quotation

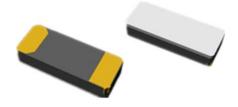
YR	32K76800	S	005
1	2	3	4

- 1. YR: Part family Code for KHz SMD crystal L3.2\*W1.5\*H0.9mm, 2 Pads
- 2. 32K76800: Frequency Range Code For 32.76800KHz
- 3. S: SMD type, Package Tape/Reel, 3000pcs/Reel
- 4. 005: Internal Control Code and Special Parameters Code Letter A~Z, a~z or digits (0-9)

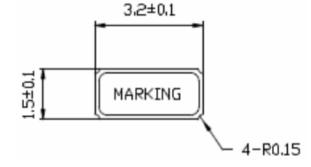
# KHZ SMD CRYSTALS 3215 TYPE YR SERIES

### **DIMENSION** (Unit: mm)





**Top View** 



### Marking

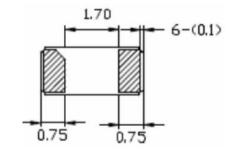
Frequency Range

or

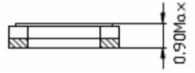
#### Marking

Internal Control Code

**Bottom View** 

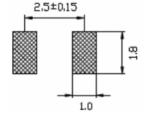


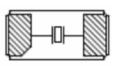
**Side View** 





Land Pattern for reference

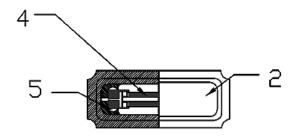


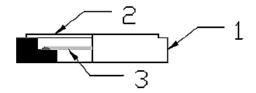




## **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

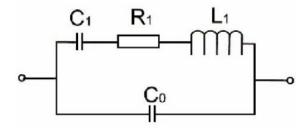
### **PRODUCT STRUCTURE**





#### Component Material Item No. Name Name 1 Crystal Case Ceramic (A1203) 2 Crystal KV (Fe/Co/Ni) Cover/Lid 3 Crystal SiO2 Chip/Blank 4 Electrode Cr、Au (Cr+Au) 5 Adhesive Resin, Ag

### **EQUIVALENT CIRCUIT**





## **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

### **ELECTRICAL PARAMETERS** – FOR DIFFERENT PART CODE- Ta = 25°C

Part Code	Frequency Range	Frequency Tolerance @ 25°C±3°C	Load Capacitance
	KHz	ppm	pF
YR32K76800S001	32.768	±20	12.5
YR32K76800S003	32.768	±20	7
YR32K76800S004	32.768	±20	6
YR32K76800S005	32.768	±20	9

### **GENERAL ELECTRICAL PARAMETERS**

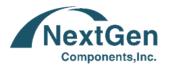
PARAMETER	UNITS	VALUE		CONDITION	
		MIN.	TYPICAL	MAX.	
Mode of Oscillation		,	AT Fundamen	tal	
Equivalent Series Resistance (ESR)	ΚΩ	-	-	70	
Parabolic Coefficient	ppm/°C²	-0.04	-	-0.02	
Drive Level (DL)	μW	-	0.1	0.5	
Shunt Capacitance (C0)	pF	-	1.1	2.0	
Dynamic Capacitance (C1)	fF	-	4.1	-	
Turnover Temperance	°C	+20	25	+30	
Insulation Resistance	ΜΩ	500			@100Vpc, ± 15VDC
Quality Factor (Q)	К	13	-	-	
Operation Temperance	°C	-40	-	+85	
Storage Temperance	°C	-55	-	+125	
Aging	ppm	-3	-	+3	Per Year



# **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

#### **RELIABILITY**

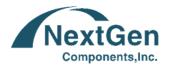
TEST ITEMS	TEST METHOD AND CONDITIONS	TEST STANDARD
High Temperature High Humidity Storage	Temperature: 60°C ± 2 °C Relative Humidity: 90%~95% RH For Time: 500 ± 12 Hours	A, C, D, G
High Temperature Storage	Temperature: 125°C ± 2°C Time: 1000±12 Hours.	В, С, G
Low Temperature Storage	Temperature: $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Time: $500 \pm 12$ Hours.	A, C, G
Temperature Cycle	The crystal unit shall be subjected to 100 successive change of temperature cycles. $ +85+4/-0^{\circ}C $ $ +25\pm2^{\circ}C $ $ -40+0/-6^{\circ}C $ $ 30\pm3min $ $ 3min. max. $ $ 1 Cycle $	A, C, G
Solderability	The solder pot temperature is 260±5°C , dwell time 2±0.6sec	F
Drop Test	Height: 180 cm; Dropped Cycle: 3 cycles; Drop it on to a concrete board for 6 Directions (X,Y,Z), that should be 1 cycle	В, С
Vibration	Frequency Range: 10Hz ~ 55Hz  Amplitude: 1.5mm±15%; Sweep time: 2~3 Minutes,  2 Hours in each direction, total 6 Hours	A, C
Leakage Test	Helium Bombing 5.0 ~5.5 Kgf/cm²; for 2 hours	E



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### **RELIABILITY**

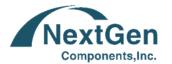
TEST ITEMS	TEST METHOD AND CONDITIONS	TEST STANDARD
Terminal Strength	Shall be pressurized at a speed of approx. 0.5mm/sec. in the direction indicated by the arrow unit the bending width reaches 3mm and held for 5 sec.  PRESSURE ROD R20  SAMPLE R5  45±2  45±2  R5	В, С
Sticking Tendency	A R0.5 Jig shall be used to apply a 10N dead load in the direction indicated by the arrow to the element and retain it for 10 sec.  JIG R0.5  SAMPLE	В, С
Element Assembly Strength	A R0.5 Jig shall be used to apply a 10N dead load in the direction indicated by the arrow to the element and retain it for 10 sec.	B, C



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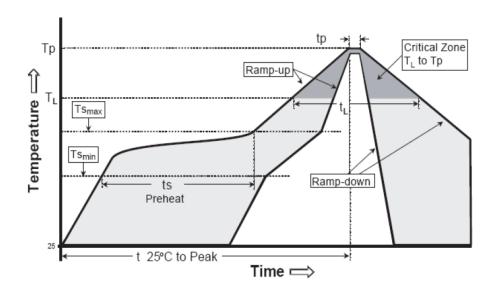
### **TEST STANDARD**

TEST STANDARD SYMBOL	SPECIFICATION	VALUE
А	Frequency Change permitted	ΔF≤10ppm
В	Frequency Change permitted	ΔF≤20ppm
С	Equivalent Series Resistance Change Permitted	ΔCI≤5KΩ or 20%
D	Insulation Resistance	>500 MΩ
E	Leak Rate Less than	<1*1E-9 Pa·m³/sec.
F	A new uniform coating of solder shall cover a Min 95% of the crystal surface	
G	Then 25 ± 2°C over 2 hours before Testing	



# KHZ SMD CRYSTALS 3215 TYPE YR SERIES

### SUGGESTED REFLOW PROFILE (For Reference No. JEDEC J-STD-020D)

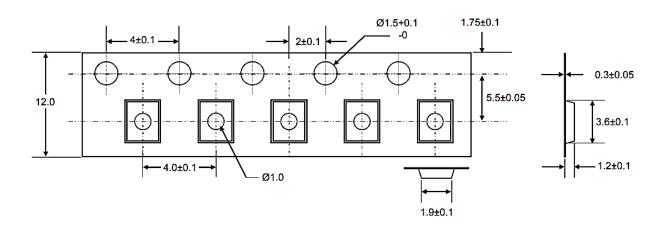


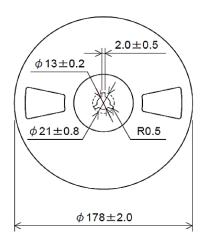
PROFILE FEATURE		PB-FREE ASSEMBLY
Average Ramp-up Rate (Ts Max to Tp)		3°C/second Max
Preheat Temperature Min (Ts Min.)		150°C
	Temperature Max (Ts Max.)	200°C
	Time (ts Min. to ts Max.)	60 ~ 120 seconds
Time maintained above	Temperature (TL)	217°C
	Time (tL)	60 ~ 150 seconds
Peak/Classification Temperature (Tp)		260 +/-5°C
Time within 5°C of actual Peak Temperature (tp)		20 ~ 40 seconds
Ramp-down rate		6 °C /Second Max.
Time 25 °C to Peak Temperature		8 minutes Max.
Suggest reflow times		3 Times Max.

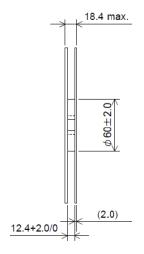
### **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

### **REEL AND TAPE DIMENSION** (Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-2 and specifications, 3000pcs/Reel







7/17/2024 10



### **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

#### **NOTES BEFORE USE**

#### **Ultrasonic Cleaning:**

General cleaning solutions or ultrasonic cleaning method may be used to clean our products. However, under certain circumstances, ultrasonic cleaning machine could generate resonance at the oscillation frequency of our products and thus deteriorate the electrical characteristics in device and even damage the overall structure of device. Therefore, verification test is recommended before cleaning.

#### **Ultrasonic Welding**

Avoid mounting and processing by Ultrasonic welding this method has a possibility of an excessive vibration spreading inside the crystal products and become the cause of characteristic deterioration and not oscillating.

#### **Storage Temperature Description**

Storage Temperature is only for the product itself, the temperature for the packing material is 5~40°C Recommended Conditions for Manual Welding Max. Temperature: 350±10°C, Time: 3 sec Max., Re-solder time: twice Max.



### **KHZ SMD CRYSTALS 3215 TYPE YR SERIES**

#### IMPORTANT NOTES AND DISCLAIMER

- ROHS COMPLIANCE: The levels of RoHS restricted materials in this product are below the maximum
  concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an
  exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for
  this product can be obtained can be obtained at Download Center.
- REACH COMPLIANCE: REACH substances of high concern (SVHCs) information is available for this product.
   Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained can be obtained at Download Center.
- 3. All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
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  express written approval by NextGen.
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Non-Cancelable/ Non-Returnable (NCNR). These products are not returnable and not refundable.